- 1N4153 and 1N4153-1 AVAILABLE IN **JAN, JANTX,** AND **JANTXV** PER MIL-PRF-19500/337
- SWITCHING DIODES
- HERMETICALLY SEALED
- METALLURGICALLY BONDED
- DOUBLE PLUG CONSTRUCTION

1N4153 and 1N4153-1

MAXIMUM RATINGS

Junction Temperature: -65°C to +175°C
Storage Temperature: -65°C to +175°C
Operating Current: 150 mA @ T_A = +25°C
Derating: 1.0 mA dc/°C Above T_A = +25°C
Forward Surge Current: 2A (pk), (tp = 1µs); 0.25A (pk), (tp = 1s)

ELECTRICAL CHARACTERISTICS @ 25°C, unless otherwise specified.

Type	V_{BR} I_R = 5 µA	V_{RWM}	I_{R1} V_R = 50 V dc T_A = 25°C	I_{R2} V_R = 50 V dc T_A = 150°C	C V_R = 0; f = 1 Mhz;	t_{rr} I_F = I_R = 10 mA dc R_L = 100 ohms
	V dc	V (pk)	nA dc	µA dc	pF	ns
1N4153-1	75	50	50	50	2.0	4

FORWARD VOLTAGE LIMITS – ALL TYPES

Limits	V_{F1} I_F = 100 µA dc	V_{F2} I_F = 250 µA dc	V_{F3} I_F = 1 mA dc	V_{F4} I_F = 2 mA dc	V_{F5} I_F = 10 mA dc	V_{F6} I_F = 20 mA dc
	V dc	V dc	V dc	V dc	V dc	V dc
minimum	0.49	0.53	0.59	0.62	0.70	0.74
maximum	0.55	0.59	0.67	0.70	0.81	0.88

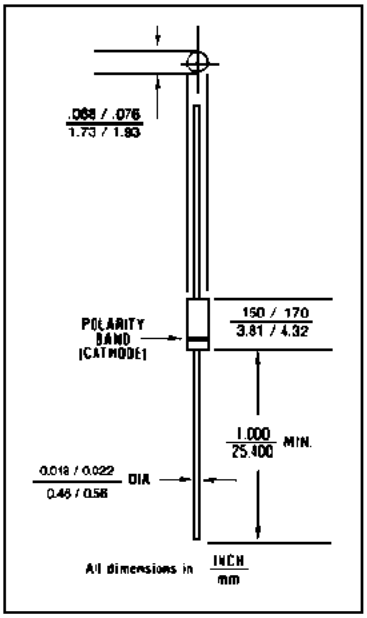

FIGURE 1

DESIGN DATA

CASE: Hermetically sealed glass case per MIL-S-19500/337 D0-35 outline

LEAD MATERIAL: Copper clad steel.

LEAD FINISH: Tin / Lead

THERMAL RESISTANCE: ($R_{\Theta JL}$): 250 °C/W maximum at L = .375

THERMAL IMPEDANCE: ($Z_{\Theta JX}$): 70 °C/W maximum

POLARITY: Cathode end is banded.

MOUNTING POSITION: Any.

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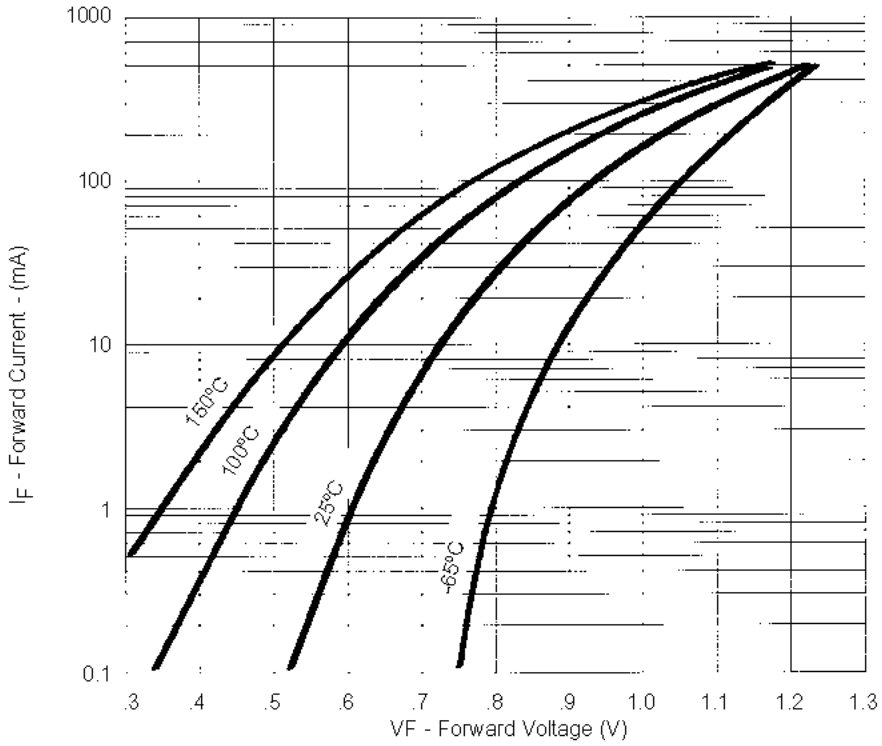
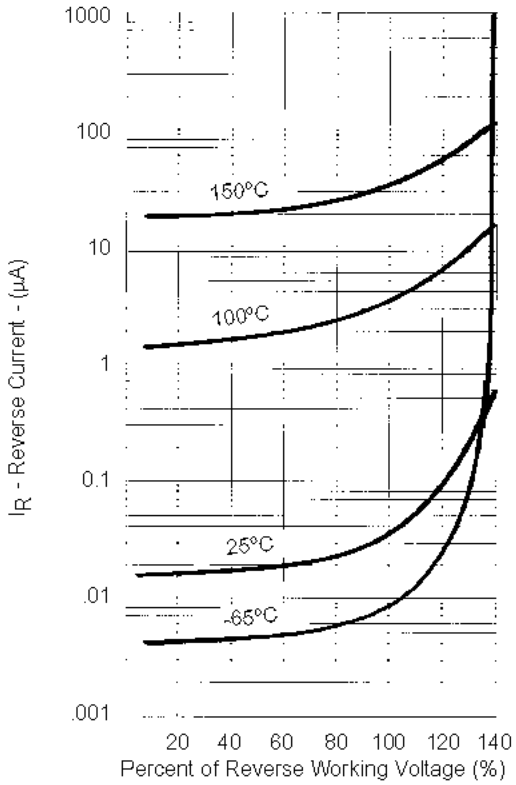


FIGURE 2
Typical Forward Current
vs Forward Voltage



NOTE : All temperatures shown on graphs are junction temperatures

FIGURE 3
Typical Reverse Current
vs Reverse Voltage